

GSM4516

30V N & P Pair Enhancement Mode MOSFET

Product Description

GSM4516, N & P Pair enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge.

These devices are particularly suited for low voltage power management, and low in-line power loss are needed in commercial industrial surface mount applications.

Features

N-Channel

- 30V/8A, $R_{DS(ON)}=15m\Omega$ @ $V_{GS}=10V$
- 30V/6A, $R_{DS(ON)}=20m\Omega$ @ $V_{GS}=4.5V$

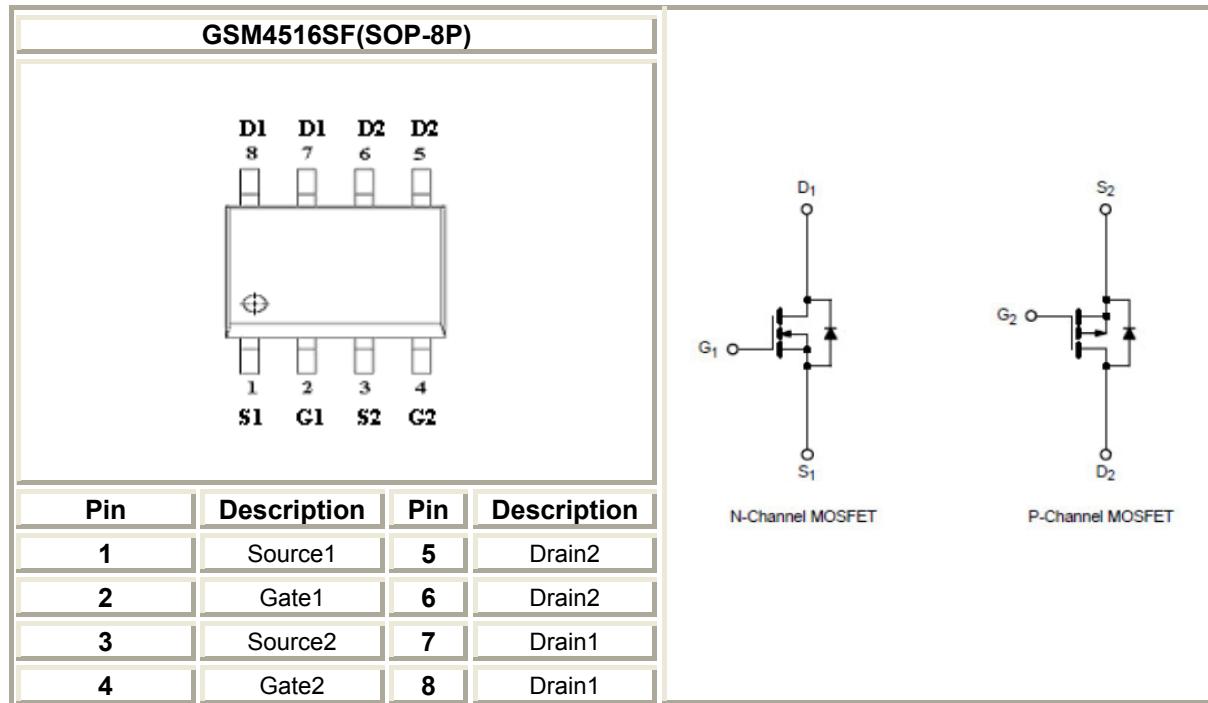
P-Channel

- -30V/-8A, $R_{DS(ON)}=28m\Omega$ @ $V_{GS}=-10V$
- -30V/-6A, $R_{DS(ON)}=37m\Omega$ @ $V_{GS}=-4.5V$

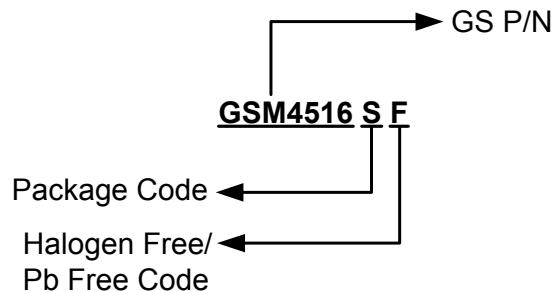
Applications

- Low Current DC/DC Conversion
- Load Switch
- CCFL Inverter
- Power Management in Notebook Computer

Packages & Pin Assignments

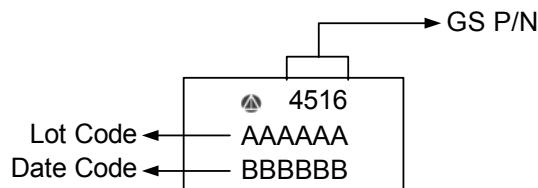


Ordering Information



Part Number	Package	Quantity Reel
GSM4516SF	SOP-8	3000 PCS

Marking Information



Absolute Maximum Ratings (N-Channel)

(T_A=25°C unless otherwise noted)

Symbol	Parameter	Typical	Unit
V _{DSS}	Drain-Source Voltage	30	V
V _{GSS}	Gate -Source Voltage	±20	V
I _D	Continuous Drain Current(T _J =150°C)	8.0	A
	T _A =25°C	8.0	
	T _A =70°C	6.0	
I _{DM}	Pulsed Drain Current	25	A
I _S	Continuous Source Current(Diode Conduction)	1.5	A
P _D	Power Dissipation	2.8	W
	T _A =25°C	2.8	
	T _A =70°C	1.8	
T _J	Operating Junction Temperature	150	°C
T _{STG}	Storage Temperature Range	-55/150	°C
R _{θJA}	Thermal Resistance-Junction to Ambient	62.5	°C/ W

Electrical Characteristics (N-Channel)

($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	30			V
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.5		1.8	
I_{GSS}	Gate Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			± 100	nA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}, V_{GS}=0\text{V}$			1	uA
		$V_{DS}=30\text{V}, V_{GS}=0\text{V}, T_J=85^\circ\text{C}$			10	
$I_{D(\text{on})}$	On-State Drain Current	$V_{DS}\geq 5\text{V}, V_{GS}=10\text{V}$	15			A
$R_{DS(\text{on})}$	Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=8\text{A}$		11	15	mΩ
		$V_{GS}=4.5\text{V}, I_D=6\text{A}$		15	20	
g_{FS}	Forward Transconductance	$V_{DS}=15\text{V}, I_D=10\text{A}$		24		S
V_{SD}	Diode Forward Voltage	$I_S=3.0\text{A}, V_{GS}=0\text{V}$		0.8	1.3	V
Dynamic						
C_{iss}	Input Capacitance	$V_{DS}=15\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$		800		pF
C_{oss}	Output Capacitance			180		
C_{rss}	Reverse Transfer Capacitance			70		
Q_g	Total Gate Charge	$V_{DS}=15\text{V}, V_{GS}=4.5\text{V}, I_D=10\text{A}$		8	12	nC
Q_{qs}	Gate-Source Charge			2.0		
Q_{qd}	Gate-Drain Charge			2.3		
$t_{d(\text{on})}$	Turn-On Time	$V_{DD}=15\text{V}, R_L=1.5\Omega, I_D=10\text{A}, V_{GEN}=10\text{V}, R_G=1\Omega$		8	15	ns
T_r				8	15	
$t_{d(\text{off})}$	Turn-Off Time			16	28	
T_f				8	16	

Absolute Maximum Ratings (P-Channel)

($T_A=25^\circ\text{C}$ unless otherwise noted)

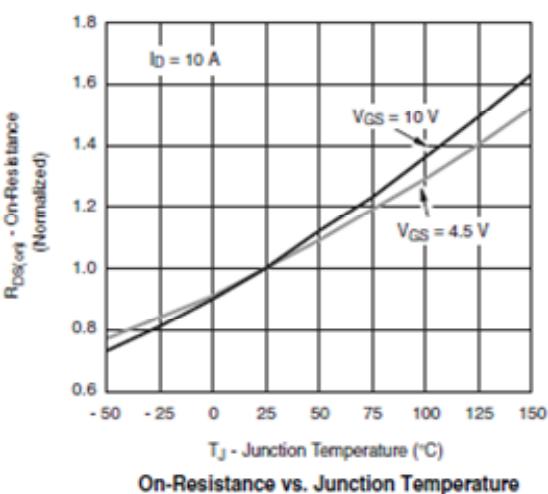
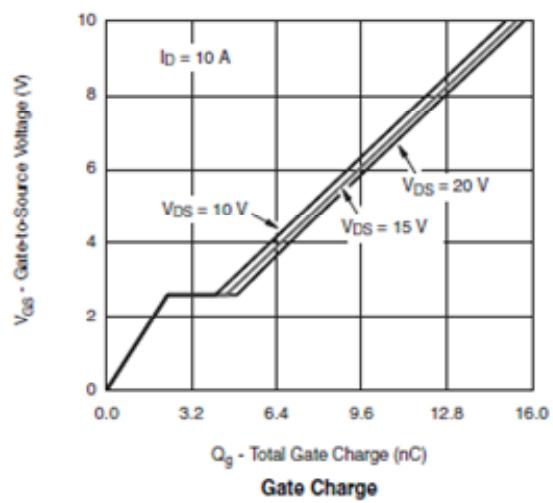
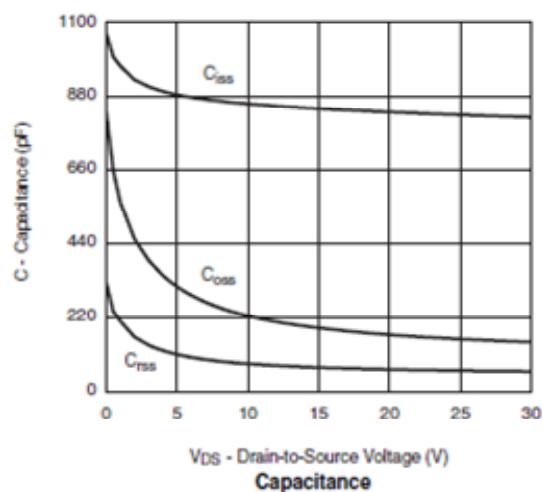
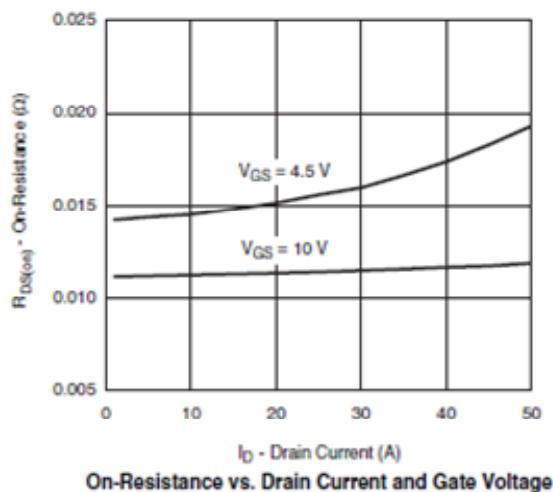
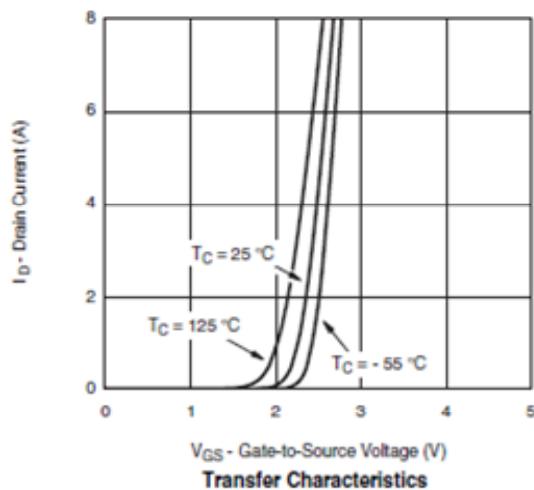
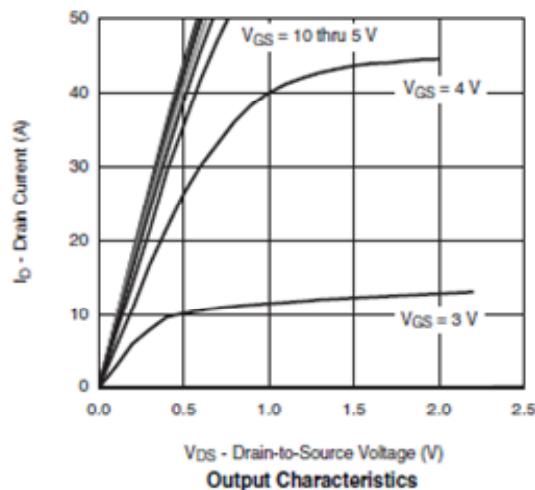
Symbol	Parameter	Typical	Unit
V_{DSS}	Drain-Source Voltage	-30	V
V_{GSS}	Gate -Source Voltage	± 20	V
I_D	Continuous Drain Current($T_J=150^\circ\text{C}$)	$T_A=25^\circ\text{C}$	-8.0
		$T_A=70^\circ\text{C}$	-6.0
I_{DM}	Pulsed Drain Current	-25	A
I_S	Continuous Source Current(Diode Conduction)	-1.7	A
P_D	Power Dissipation	$T_A=25^\circ\text{C}$	2.8
		$T_A=70^\circ\text{C}$	1.8
T_J	Operating Junction Temperature	150	°C
T_{STG}	Storage Temperature Range	-55/150	°C
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	62.5	°C/ W

Electrical Characteristics (P-Channel)

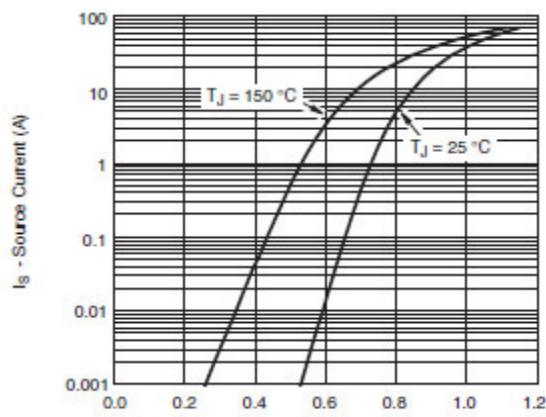
($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=-250\mu\text{A}$	-30			V
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-0.5		-1.8	
I_{GSS}	Gate Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$			± 100	nA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-24\text{V}, V_{GS}=0\text{V}$			-1	uA
		$V_{DS}=-24\text{V}, V_{GS}=0\text{V}, T_J=85^\circ\text{C}$			-30	
$I_{D(\text{on})}$	On-State Drain Current	$V_{DS} \leq -10\text{V}, V_{GS}=-10\text{V}$	-30			A
		$V_{DS} \leq -5\text{V}, V_{GS}=-4.5\text{V}$	-5			
$R_{DS(\text{on})}$	Drain-Source On-Resistance	$V_{GS}=-10\text{V}, I_D=-8\text{A}$		24	28	mΩ
		$V_{GS}=-4.5\text{V}, I_D=-6\text{A}$		30	37	
g_{FS}	Forward Transconductance	$V_{DS}=-10\text{V}, I_D=-9.0\text{A}$		22		S
V_{SD}	Diode Forward Voltage	$I_S=-1.7\text{A}, V_{GS}=0\text{V}$		-0.7	-1.3	V
Dynamic						
C_{iss}	Input Capacitance	$V_{DS}=-15\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$		950		pF
C_{oss}	Output Capacitance			200		
C_{rss}	Reverse Transfer Capacitance			175		
Q_g	Total Gate Charge	$V_{DS}=-15\text{V}, V_{GS}=-4.5\text{V}, I_D=-6.0\text{A}$		10	18	nC
Q_{gs}	Gate-Source Charge			1.6		
Q_{gd}	Gate-Drain Charge			3.0		
$t_{d(on)}$	Turn-On Time	$V_{DD}=-15\text{V}, R_L=15\Omega, I_D=-5.0\text{A}, V_{GEN}=-10\text{V}, R_G=6\Omega$		8	18	ns
T_r				8	18	
$t_{d(off)}$	Turn-Off Time			25	50	
T_f				25	35	

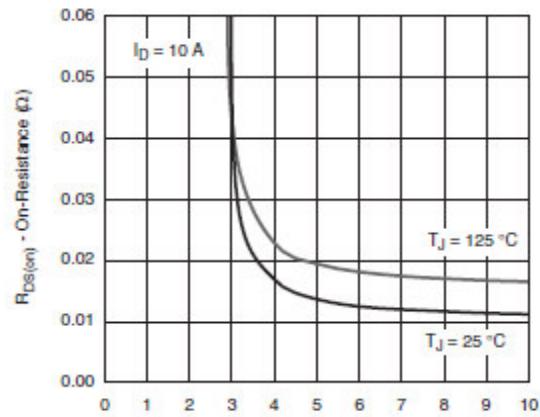
Typical Performance Characteristics (N-Channel)



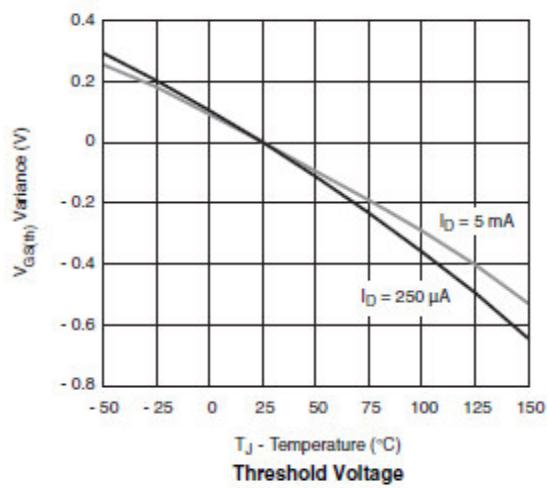
Typical Performance Characteristics (N-Channel)



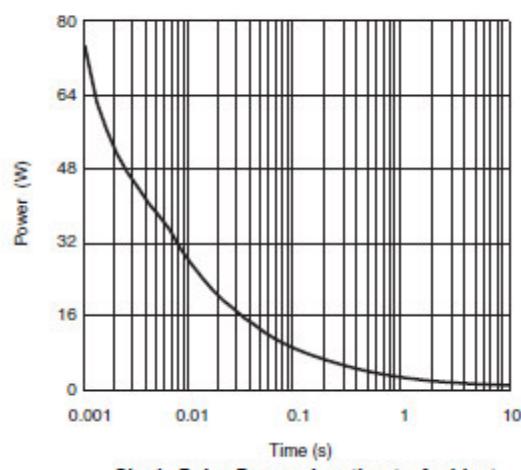
V_{SD} - Source-to-Drain Voltage (V)
Source-Drain Diode Forward Voltage



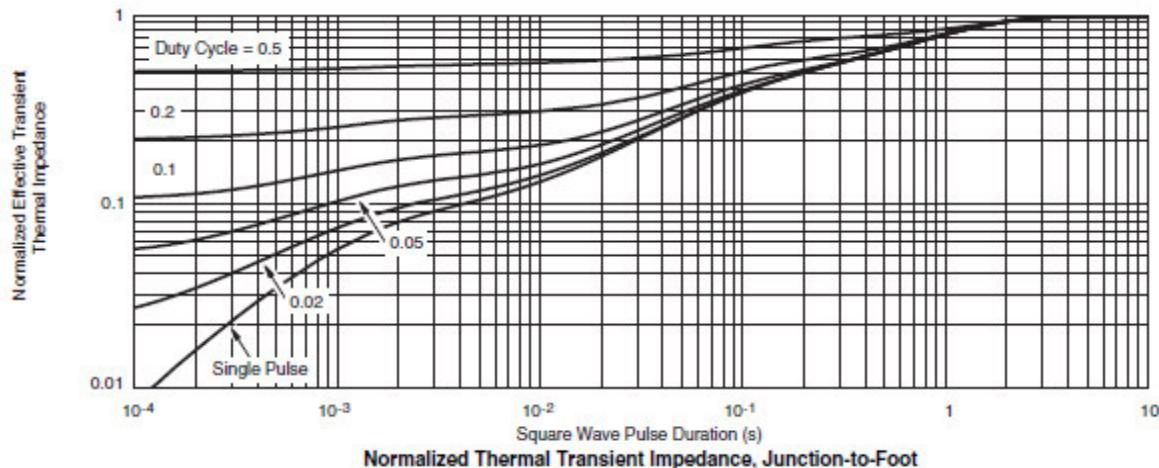
V_{GS} - Gate-to-Source Voltage (V)
On-Resistance vs. Gate-to-Source Voltage



T_J - Temperature ($^\circ\text{C}$)
Threshold Voltage

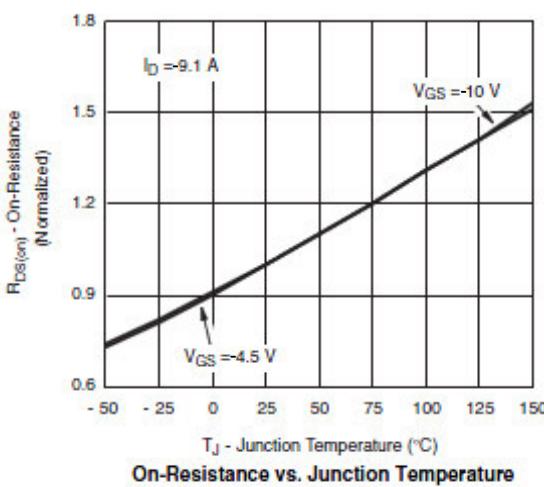
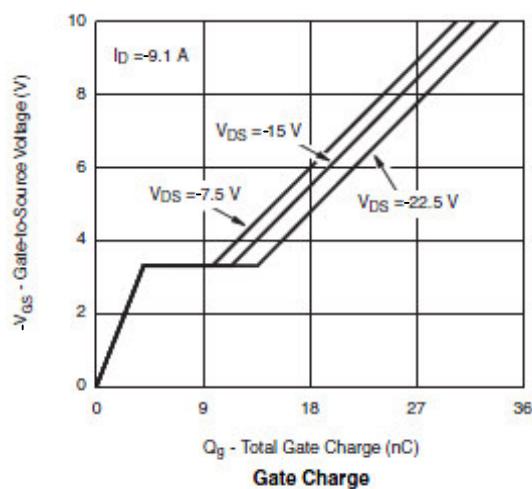
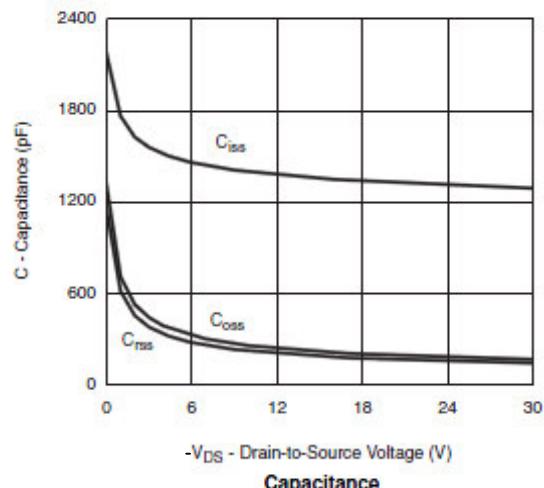
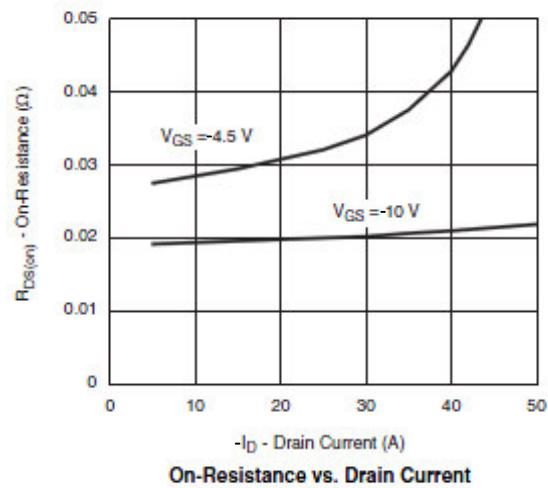
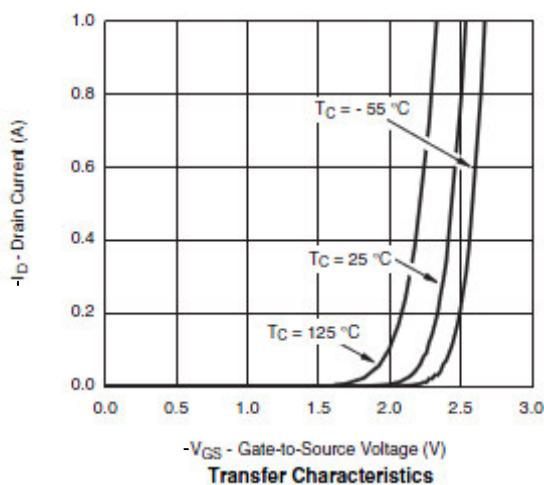
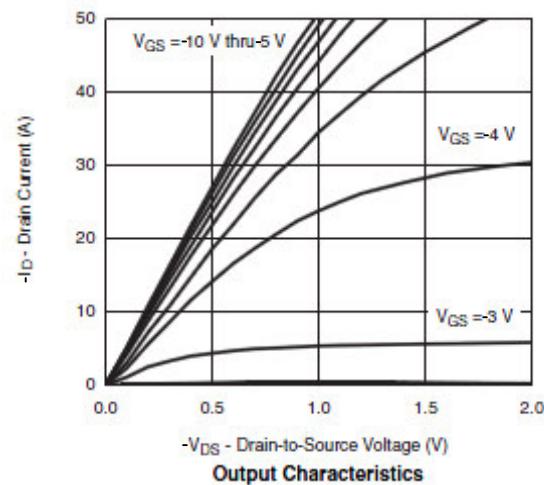


Single Pulse Power, Junction-to-Ambient

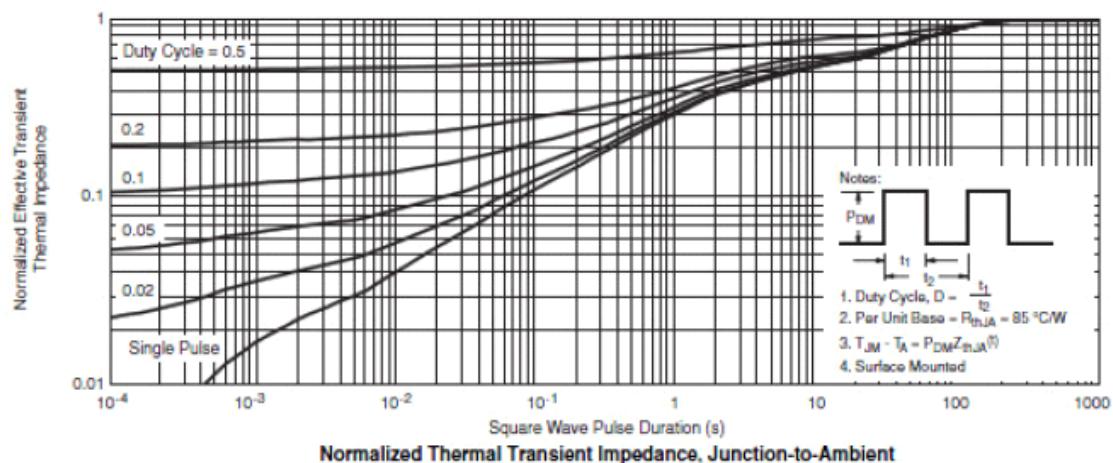
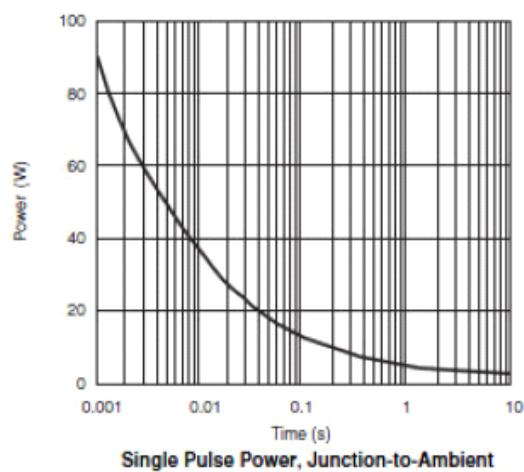
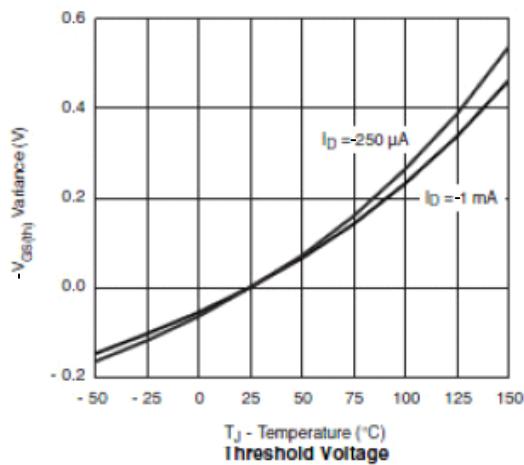
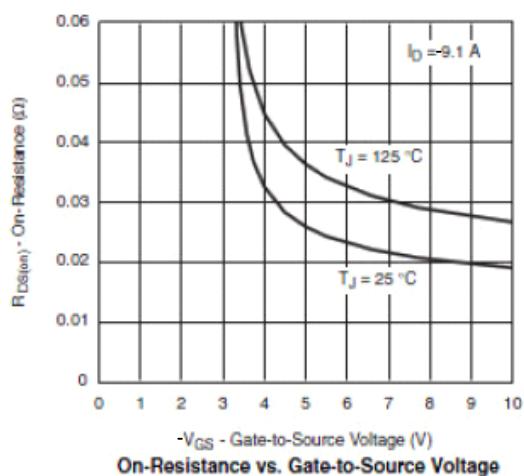
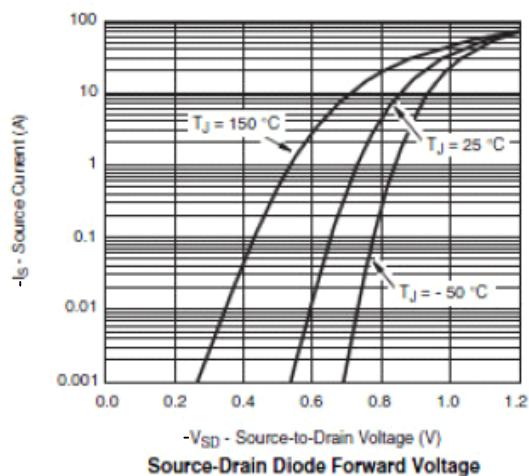


Normalized Thermal Transient Impedance, Junction-to-Foot

Typical Performance Characteristics (P-Channel)

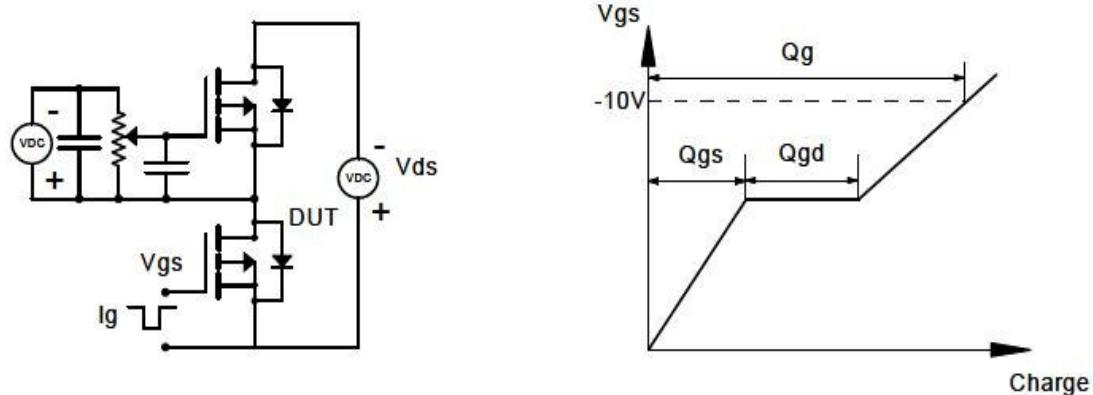


Typical Performance Characteristics (P-Channel)

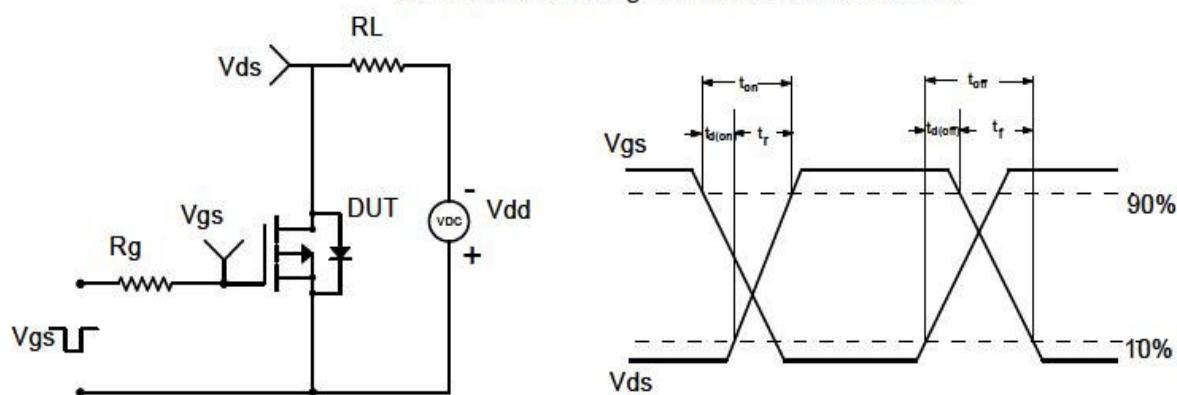


Typical Performance Characteristics

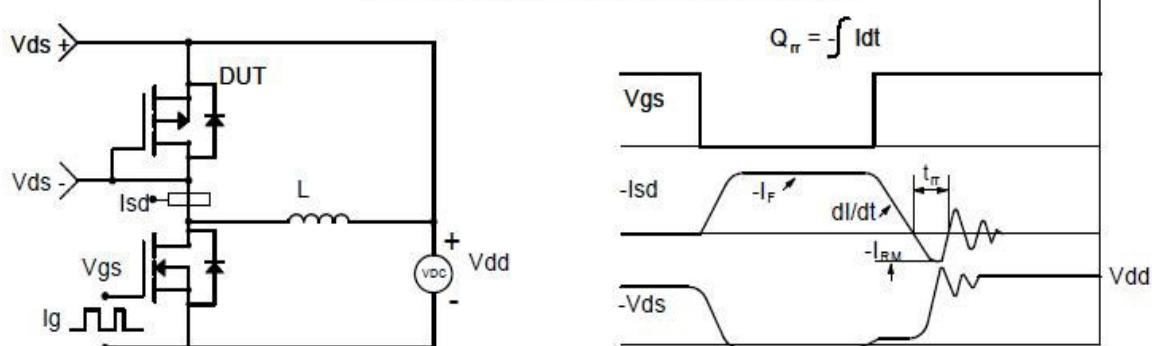
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

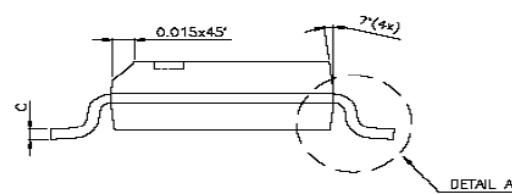
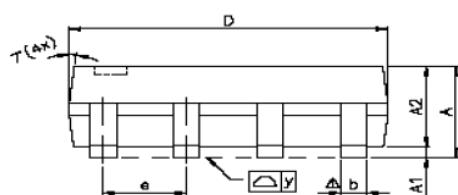
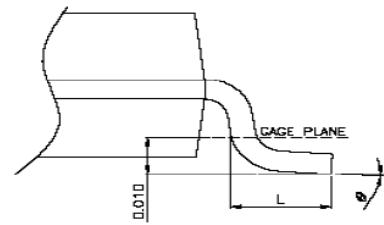
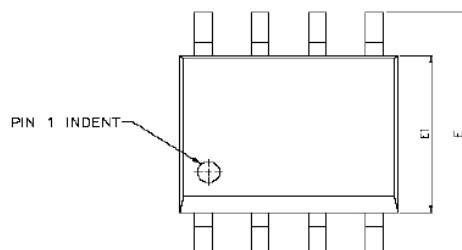


Diode Recovery Test Circuit & Waveforms



Package Dimension

SOP-8P PLASTIC PACKAGE



Dimensions

SYMBOL	Millimeters			Inches		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.47	1.60	1.73	0.058	0.063	0.068
A1	0.10	-	0.25	0.004	-	0.010
A2	-	1.45	-	-	0.057	-
b	0.33	0.41	0.51	0.013	0.016	0.020
C	0.19	0.20	0.25	0.0075	0.008	0.0098
D	4.80	4.85	4.95	0.189	0.191	0.195
E	5.80	6.00	6.20	0.228	0.236	0.244
E1	3.80	3.90	4.00	0.150	0.154	0.157
e	-	1.27	-	-	0.050	-
L	0.38	0.71	1.27	0.015	0.028	0.050
Δy	-	-	0.076	-	-	0.003
θ	0°	-	8°	0°	-	8°

GSM4516

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